



Material Content Data Sheet



Sales Product Name		BSZ013NE2LS5I		Issued		25. September 2017		
MA#		MA001301102						
Package		PG-TSDSON-8-26		Weight*		35.85 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	1.75	1.75	17547	17547
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		101	
	non noble metal	zinc	7440-66-6	0.015	0.04		405	
	non noble metal	iron	7439-89-6	0.291	0.81		8109	
wire	non noble metal	copper	7440-50-8	11.804	32.93	33.79	329253	337868
	non noble metal	copper	7440-50-8	0.013	0.04	0.04	354	354
	encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		977
plastics	plastics	epoxy resin	-	1.805	5.03		50333	
	inorganic material	silicondioxide	60676-86-0	15.680	43.73	48.86	437356	488666
	leadfinish	non noble metal	tin	7440-31-5	0.400	1.12	1.12	11163
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	567	567
solder	noble metal	silver	7440-22-4	0.023	0.07		653	
	non noble metal	tin	7440-31-5	0.019	0.05		523	
	non noble metal	lead	7439-92-1	0.895	2.50	2.62	24952	26128
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		35	
	non noble metal	zinc	7440-66-6	0.005	0.01		141	
	non noble metal	iron	7439-89-6	0.101	0.28		2825	
	non noble metal	copper	7440-50-8	4.112	11.47	11.76	114706	117707
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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